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Author Correction: Lattice strain-enhanced exsolution of nanoparticles in thin films

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Correction to: *Nature Communications* <https://doi.org/10.1038/s41467-019-09395-4>, published online 1 April 2019.

The original version of this Article contained an error in the Data Availability section, which incorrectly read ‘The data that support the findings of this study are available from the corresponding authors upon request.’ The correct version replaces this sentence with ‘The research data underpinning this publication can be accessed at <https://doi.org/10.17630/21d12144-58ef-4f82-acd0-ba3c9a44ed72>’. This has been corrected in both the PDF and HTML versions of the Article.

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